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# MAX77826

# Power Management IC

## General Description

The MAX77826 is a subpower management IC for the latest 3G/4G smartphones and tablets. The MAX77826 contains a high-efficiency BUCK regulator, a BUCK BOOST regulator and 15 LDOs to power up peripherals. The MAX77826 also provides power on/off control logic and an I<sup>2</sup>C serial interface to program individual regulator output voltages and on/off control for complete flexibility.

The linear regulators support a remote cap feature and provide greater than 70dB PSRR and less than 45 $\mu$ V<sub>RMS</sub> noise.

The MAX77826 features I<sup>2</sup>C-compatible, 2-wire serial interface that comprises a bidirectional serial data line (SDA) and a serial clock line (SCL). The MAX77826 supports SCL clock rates up to 3.4MHz.

## Applications

- GSM, GPRS, EDGE, CDMA WCDMA, and LTE Smartphones and Tablets

**Ordering Information** appears at end of data sheet.

## Benefits and Features

- Compact Total Solution Size Allows More Peripheral Devices in Smartphones and Tablets
  - 3A High-Efficiency BUCK Regulator
    - DVS (Dynamic Voltage Scaling) Through HS I<sup>2</sup>C
    - $\pm 1\%$  (typ) Output Voltage DC Accuracy
    - Low Power Mode
  - 2A BUCK BOOST Regulator
  - 15 Linear Regulators with Remote Cap
    - 3 NMOS LDOs ( $V_{OUT}$  Range: 0.6V to 2.1875V with 12.5mV Step)
      - 1 x 150mA
      - 1 x 450mA
      - 1 x 600mA
    - 6 PMOSLV LDOs ( $V_{OUT}$  Range: 0.8V to 3.975V with 25mV Step)
      - 3 x 150mA
      - 3 x 300mA
    - 6 PMOSLS LDOs ( $V_{OUT}$  Range: 0.8V to 3.975V with 25mV Step)
      - 3 x 150mA
      - 3 x 300mA
  - $\pm 1.5\%$  Typical Output Voltage DC Accuracy
  - 70dB PSRR at 1kHz
  - Low Power Mode with 2 $\mu$ A (typ) for all LDOs
- Simple Management of Power-Up/Down Sequence, Output Voltage Setting, and Fault Detection
  - High-Speed (Up to 3.4MHz) I<sup>2</sup>C Serial Interface

### Absolute Maximum Ratings

SYS, V <sub>IO</sub> , INL1, INL2, INL3, INL4, INL5 to GND .....	-0.3V to +6.0V	LDO1, LDO2 to GND .....	-0.3V to (V <sub>INL1</sub> + 0.3V)
INB to PGND .....	-0.3V to +6.0V	LDO3 to GND .....	-0.3V to (V <sub>INL2</sub> + 0.3V)
INBB, OUTBB to PGND .....	-0.3V to +6.0V	LDO4, LDO5, LDO6, LDO7, LDO8, LDO9 to GND .....	-0.3V to (V <sub>INL3</sub> + 0.3V)
PGND, PGNDDB to GND .....	-0.3V to +0.3V	LDO10, LDO11 to GND .....	-0.3V to (V <sub>INL4</sub> + 0.3V)
IRQB, CE, SDA, SCL to GND .....	-0.3V to (V <sub>IO</sub> + 0.3V)	LDO12, LDO13, LDO14, LDO15 to GND .....	-0.3V to (V <sub>INL5</sub> + 0.3V)
FB_B, ENBB, ENB, ENL12, REFBYP to GND .....	-0.3V to (V <sub>SYS</sub> + 0.3V)	LXB Continuous RMS Current (Note 1) .....	3A
FB_BB to PGNDDB .....	-0.3V to (V <sub>OUTBB</sub> + 0.3V)	LXBB1/LXBB2 Continuous RMS Current (Note 1) .....	3.3A
LXB to PGND .....	-0.3V to (V <sub>INB</sub> + 0.3V)	Operating Temperature Range .....	-40°C to +85°C
LXBB1 to PGNDDB .....	-0.3V to (V <sub>INBB</sub> + 0.3V)	Junction Temperature .....	+150°C
LXBB2 to PGNDDB .....	-0.3V to (V <sub>OUTBB</sub> + 0.3V)	Storage Temperature Range .....	-65°C to +150°C
		Soldering Temperature (reflow) .....	+260°C

**Note 1:** LX\_ node has internal clamp diodes to PGND\_ and INB\_. Applications that give forward bias to these diodes should ensure that the total power loss does not exceed IC's package power dissipation limits.

### Package Thermal Characteristics (Note 2)

WLP  
Junction-to-Ambient Thermal Resistance (θ<sub>JA</sub>) .....37°C/W

**Note 2:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

### General Electrical Characteristics

(V<sub>SYS</sub> = V<sub>IN\_</sub> = +3.7V, V<sub>IO</sub> = 1.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Shutdown Supply Current	I <sub>SHDN_SYS</sub>	CE = low		2.5	10	μA
Standby Current	I <sub>Q_SYS</sub>	CE = high and all regulators are off		35		μA
Shutdown V <sub>IO</sub> Current	I <sub>SHDN_VIO</sub>	All regulators are off		0		μA
No Load Supply Current 1	I <sub>NO_LOAD1</sub>	BUCK is on in normal mode (no switching)		60		μA
No Load Supply Current 2	I <sub>NO_LOAD2</sub>	BUCK and BUCK BOOST are on in normal mode (no switching)		120		μA
No Load Supply Current 3	I <sub>NO_LOAD3</sub>	All regulators are on in normal mode (no switching)		400	700	μA
<b>V<sub>SYS</sub> UNDERVOLTAGE LOCKOUT</b>						
V <sub>SYS</sub> Undervoltage Lockout Threshold	V <sub>UVLO_R</sub>	V <sub>SYS</sub> rising	2.375	2.50	2.625	V
	V <sub>UVLO_F</sub>	V <sub>SYS</sub> falling (default)		2.05		
<b>REFERENCE</b>						
REFBYP Output Voltage			0.786	0.80	0.814	V
REFBYP Supply Rejection		2.7V ≤ V <sub>SYS</sub> ≤ 5.5V		0.2		mV/V

**General Electrical Characteristics (continued)**(V<sub>SYS</sub> = V<sub>IN\_</sub> = +3.7V, V<sub>IO</sub> = 1.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>THERMAL SHUTDOWN</b>						
Thermal Shutdown Threshold	T <sub>SHDN</sub>	T <sub>J</sub> rising, 15°C hysteresis		+165		°C
Thermal Interrupt at +120°C	T <sub>120</sub>	T <sub>J</sub> rising, 15°C hysteresis		+120		°C
Thermal Interrupt at +140°C	T <sub>140</sub>	T <sub>J</sub> rising, 15°C hysteresis		+140		°C
<b>LOGIC AND CONTROL INPUTS</b>						
Input Low Level	V <sub>IL</sub>	ENB, ENBB, ENL12	V <sub>SYS</sub> ≤ 4.5V T <sub>A</sub> = +25°C		0.4	V
		CE	T <sub>A</sub> = +25°C		0.3 x V <sub>IO</sub>	
Input High Level	V <sub>IH</sub>	ENB, ENBB, ENL12	V <sub>SYS</sub> ≤ 4.5V T <sub>A</sub> = 25°C	1.2		V
		CE	T <sub>A</sub> = +25°C	0.7 x V <sub>IO</sub>		
Logic Input Leakage Current	I <sub>LEAK</sub>	CE (0V < V <sub>IO</sub> < 1.8V)	T <sub>A</sub> = +25°C	-1	+1	μA
			T <sub>A</sub> = +85°C		0.1	
IRQB Output Low Voltage	V <sub>OL</sub>	I <sub>SINK</sub> = 1mA			0.4	V
IRQB Output High Leakage	I <sub>OZH</sub>	V <sub>IO</sub> = 5.5V	T <sub>A</sub> = +25°C	-1	+1	μA
			T <sub>A</sub> = +85°C		0.1	
<b>INTERNAL PULLDOWN RESISTANCE</b>						
ENB, ENBB, ENL12	R <sub>PD</sub>	Pulldown resistor to GND	400	800	1600	kΩ

## I<sup>2</sup>C Electrical Characteristics

(V<sub>SYS</sub> = V<sub>IN\_</sub> = +3.7V, V<sub>IO</sub> = 1.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>POWER SUPPLY</b>						
V <sub>IO</sub> Voltage	V <sub>IO</sub>		1.7		3.6	V
<b>SDA AND SCL I/O STAGES</b>						
SCL, SDA Input High Voltage	V <sub>IH</sub>		0.7 x V <sub>IO</sub>			V
SCL, SDA Input Low Voltage	V <sub>IL</sub>				0.3 x V <sub>IO</sub>	V
SCL, SDA Input Hysteresis	V <sub>HYS</sub>		0.05 x V <sub>IO</sub>			V
SCL, SDA Input Current	I <sub>I</sub>	V <sub>IO</sub> = 3.7V	-10		+10	μA
SDA Output Low Voltage	V <sub>OL</sub>	I <sub>SINK</sub> = 20mA			0.4	V
SCL, SDA Pin Capacitance	C <sub>I</sub>		10			pF
Output Fall Time from V <sub>IO</sub> to 0.3 x V <sub>IO</sub>	t <sub>OF</sub>				120	ns
<b>I<sup>2</sup>C-COMPATIBLE INTERFACE TIMING (STANDARD, FAST, AND FAST MODE PLUS) (Note 3)</b>						
Clock Frequency	f <sub>SCL</sub>				1000	kHz
Hold Time (REPEATED) START Condition	t <sub>HD;STA</sub>		0.26			μs
CLK Low Period	t <sub>LOW</sub>		0.5			μs
CLK High Period	t <sub>HIGH</sub>		0.26			μs
Setup Time REPEATED START Condition	t <sub>SU;STA</sub>		0.26			μs
DATA Hold Time	t <sub>HD;DAT</sub>		0			μs
DATA Setup Time	t <sub>SU;DAT</sub>		50			ns
Setup Time for STOP Condition	t <sub>SU;STO</sub>		0.26			μs
Bus-Free Time Between STOP and START	t <sub>BUF</sub>		0.5			μs
Capacitive Load for Each Bus Line	C <sub>B</sub>				550	pF
Maximum Pulse Width of Spikes That Must Be Suppressed by the Input Filter				50		ns

**I<sup>2</sup>C Electrical Characteristics (continued)**(V<sub>SYS</sub> = V<sub>IN\_</sub> = +3.7V, V<sub>IO</sub> = 1.8V, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	C <sub>B</sub> = 100pF			C <sub>B</sub> = 400pF			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
<b>I<sup>2</sup>C-COMPATIBLE INTERFACE TIMING (HS MODE)</b>									
Clock Frequency	f <sub>SCL</sub>				3.4			1.7	MHz
Set-Up Time REPEATED START Condition	t <sub>SU;STA</sub>		160			160			ns
Hold Time (REPEATED) START Condition	t <sub>HD;STA</sub>		160			160			ns
CLK Low Period	t <sub>LOW</sub>		160			320			ns
CLK High Period	t <sub>HIGH</sub>		60			120			ns
DATA Setup time	t <sub>SU;DAT</sub>		10			10			ns
DATA Hold Time	t <sub>HD;DAT</sub>			35			75		ns
SCL Rise Time (Note 3)	t <sub>RCL</sub>	T <sub>A</sub> = +25°C	10		40	20		80	ns
Rise Time of SCL Signal After a REPEATED START Condition and After an Acknowledge Bit (Note 3)	t <sub>RCL1</sub>	T <sub>A</sub> = +25°C	10		80	20		160	ns
SCL Fall Time (Note 3)	t <sub>FCL</sub>	T <sub>A</sub> = +25°C	10		40	20		80	ns
SDA Rise Time (Note 3)	t <sub>rDA</sub>	T <sub>A</sub> = +25°C			80			160	ns
SDA Fall Time (Note 3)	t <sub>fDA</sub>	T <sub>A</sub> = +25°C			80			160	ns
Set-Up Time for STOP Condition	t <sub>SU;STO</sub>		160			160			ns
Capacitive Load for Each Bus Line	C <sub>B</sub>				100			400	pF
Maximum Pulse Width of Spikes That Must Be Suppressed by the Input Filter				10			10		ns

## BUCK Electrical Characteristics

( $V_{SYS} = V_{INB} = +3.7V$ ,  $V_{FB\_B} = V_{OUT} = 1.25V$ ,  $T_A = -40^\circ C$  to  $+85^\circ C$ , typical values are at  $T_A = +25^\circ C$ , unless otherwise noted.) (Note 4)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	Parametric		2.6		5.5	V
Shutdown Supply Current (Note 3)				0.1		$\mu A$
Supply Quiescent Current (Note 3)	No switching, No load	Normal mode		22		$\mu A$
		Low power mode		8		
Output Voltage Range	I <sup>2</sup> C-programmable 6.25mV step		0.5		1.8	V
Output Voltage Accuracy	$V_{INB} = 2.6V$ to $4.5V$ , $V_{OUT} = 1.25V$ , no load	PWM mode, $T_A = +25^\circ C$	-1.0		+1.0	%
		Low power mode	-3.0		+4.0	
Line Regulation	$V_{INB} = 2.6V$ to $4.5V$			0.200		%/V
Load Regulation (Note 3)	$V_{OUT} = 1.25V$			0.125		%/A
Transient Load Response, VDROOP (Note 3)	$V_{OUT} = 1.25V$ , I <sub>OUT</sub> changes from 0A to 1.5A in 6 $\mu s$ , C <sub>OUT_ACTUAL</sub> = 22 $\mu F$ , L = 0.47 $\mu H$			-50		mV
Soft-Start Slew Rate				14		mV/ $\mu s$
Output Voltage Ramp-Up Slew Rate	RAMP[1:0] = 00b (default)			12.5		mV/ $\mu s$
	RAMP[1:0] = 01b			25		
	RAMP[1:0] = 10b			50		
	RAMP[1:0] = 11b			100		
Maximum Output Current	Normal mode		3000			mA
	Low power mode		10			
Peak Current Limit			3.30	4.25	5.50	A
Valley Current Limit				3.825		A
Negative Current Limit				1.000		A
N-FET Zero-Crossing Threshold	Skip mode			20		mA
Switching Frequency			1.8	2	2.2	MHz
Turn-On Delay Time	EN signal to LX switching with bias ON			30		$\mu s$
HS PMOS RDSON	$V_{INB} = 3.7V$ , INB to LX, I <sub>LX</sub> = 200mA			60		m $\Omega$
LS NMOS RDSON	$V_{INB} = 3.7V$ , LX to PGNDB, I <sub>LX</sub> = 200mA			35		m $\Omega$
Output Active Discharge Resistance	Output disabled, resistance from FB_B to PGNDB			100		$\Omega$
LX Leakage	$V_{LXB} = 5.5V$ or 0V	$T_A = +25^\circ C$	-1	0.1	+1	$\mu A$
		$T_A = +85^\circ C$		1		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	$V_{OUT}$ POK rising threshold			90		%
Output POK Hysteresis	$V_{OUT}$ when V <sub>POK</sub> switches			5		%

## BUCK BOOST Electrical Characteristics

( $V_{INBB} = +3.7V$ ,  $V_{OUTBB} = +3.5V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , typical values are at  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
<b>GENERAL</b>						
Operating Input Voltage Range	Supplied from $V_{SYS}$		2.6		5.5	V
Shutdown Supply Current	$V_{INBB} = 5.5V$ , $V_{OUTBB} = 0V$	$T_A = +25^{\circ}C$		0.01		$\mu A$
		$T_A = +85^{\circ}C$		1		
Input Supply Current	Enabled, no load	HSKIP mode (no switching)		60		$\mu A$
		FPWM mode (switching)		9		mA
Active Discharge Resistance				100		$\Omega$
Thermal Shutdown	$T_A$ rising, $20^{\circ}C$ hysteresis			+165		$^{\circ}C$
<b>H-BRIDGE</b>						
Maximum Output Current (Note 6)	$V_{INBB} = 3.0V$ , $V_{OUTBB} = 3.5V$		2000			mA
	$V_{INBB} = 2.6V$ , $V_{OUTBB} = 3.5V$		1500			
Default Output Voltage	No load, $BB\_VOUT[6:0] = 0x48$			3.5		V
Output Voltage Accuracy	$BB\_VOUT[6:0] = 0x48$ , no load	PWM mode	-1.0		+1.0	%
		HSKIP mode $T_A = +25^{\circ}C$	-1.0		+4.0	
Output Voltage Range	I <sup>2</sup> C programmable (12.5mV step)		2.6		4.1875	V
Line Regulation	$V_{INBB} = 2.6V$ to $5.5V$			0.200		%/V
Load Regulation (Note 6)	$V_{OUTBB} = 3.5V$			0.125		%/A
Transient Load Response, $V_{DROOP}$ (Note 6)	$V_{INBB} = 3.8V$ , $V_{OUTBB} = 3.5V$ , $I_{OUT}$ changes from 10mA to 1A in 10 $\mu s$ , $C_{OUT\_ACTUAL} = 47\mu F$ , $L = 1\mu H$			-100		mV
Output Overvoltage Threshold	With respect to $V_{OUTBB}$	$BB\_OVP\_TH[1:0] = 01b$		110		%
		$BB\_OVP\_TH[1:0] = 10b$		115		
		$BB\_OVP\_TH[1:0] = 11b$ (default)		120		
Switching Frequency	2-phase BUCK or BOOST mode		1.6	1.8	2.0	MHz
	3-phase mode			0.9		
LXBB1, LXBB2 Leakage Current	$V_{LXBB1/2} = 0V$ or $5.5V$ , $V_{OUTBB} = 5.5V$ , $V_{SYS} =$ $V_{INBB} = 5.5V$	$T_A = +25^{\circ}C$		0.1	1	$\mu A$
		$T_A = +85^{\circ}C$		0.2		
LXBB1/2 Current Limit			3.5	4.5	5.5	A
PMOS On-Resistance	$I_{LXBB} = 100mA$ , per switch			65		m $\Omega$
NMOS On-Resistance	$I_{LXBB} = 100mA$ , per switch			55		m $\Omega$



**BUCK BOOST Electrical Characteristics (continued)**(V<sub>INBB</sub> = +3.7V, V<sub>OUTBB</sub> = +3.5V, T<sub>A</sub> = -40°C to +85°C, typical values are at T<sub>A</sub> = +25°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Minimum Effective Output Capacitance	0μA < I <sub>OUT</sub> < 2000mA		16		μF
Turn-On Delay Time	From ENBB asserting to LXBB Switching with bias on		6		μs
Soft-Start Time	V <sub>OUTBB</sub> = 3.5V, I <sub>OUT</sub> = 10mA		40		μs
<b>POWER-OK COMPARATOR</b>					
Output POK Trip Level	V <sub>OUTBB</sub> POK rising threshold		80		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches		5		%

**LDO Electrical Characteristics**

LDO NO.	TYPE	V <sub>OUT</sub> RANGE (V)	STEP SIZE (mV)	I <sub>OUT</sub> (max, mA)	DEFAULT V <sub>OUT</sub> (V)	DEFAULT ON/OFF	INPUT PIN	C <sub>OUT</sub> (μF)
1	NMOS	0.6–2.1875	12.5	600	1.0	Off	INL1	4.7
2	NMOS	0.6–2.1875	12.5	150	1.0	Off	INL1	1
3	NMOS	0.6–2.1875	12.5	450	1.0	Off	INL2	4.7
4	PMOSLV	0.8–3.975	25	300	1.5	Off	INL3	4.7
5	PMOSLV	0.8–3.975	25	300	1.8	Off	INL3	4.7
6	PMOSLV	0.8–3.975	25	150	1.8	Off	INL3	2.2
7	PMOSLV	0.8–3.975	25	300	1.8	Off	INL3	4.7
8	PMOSLV	0.8–3.975	25	150	1.8	Off	INL3	2.2
9	PMOSLV	0.8–3.975	25	150	1.8	Off	INL3	2.2
10	PMOSLS	0.8–3.975	25	300	2.8	Off	INL4	2.2
11	PMOSLS	0.8–3.975	25	150	2.8	Off	INL4	2.2
12	PMOSLS	0.8–3.975	25	300	3.3	Off	INL5	2.2
13	PMOSLS	0.8–3.975	25	300	3.3	Off	INL5	2.2
14	PMOSLS	0.8–3.975	25	150	3.3	Off	INL5	2.2
15	PMOSLS	0.8–3.975	25	150	3.3	Off	INL5	2.2

**Note:** LDO12 can also be enabled/disabled by external logic inputs, ENL12.

**LDO1 (600mA NMOS)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 4.7μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub> must be lower than or equal to V <sub>SYS</sub>		V <sub>OUT</sub>		V <sub>SYS</sub>	V
	V <sub>SYS</sub>		2.6		5.5	
	(Note 7)		1.5			
Input Supply Current	Normal mode, no load			2		μA
	Low power mode, no load			2		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			30		μA
	Low power mode, no load			4		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.6		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			2.1875		
	Least significant step size			0.0125		
Output Voltage Accuracy	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		600			mA
	Low power mode		5			
Load Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V)	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>		0.5		%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA		0.5		
Line Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), I <sub>OUT</sub> = 0.1mA	Normal mode		0.05		%V
		Low power mode		0.05		
Dropout Voltage	Normal mode, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>	V <sub>SYS</sub> - V <sub>OUT</sub> = 2.5V		60	150	mV
		V <sub>SYS</sub> - V <sub>OUT</sub> = 1.5V		100		
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT(TARGET)</sub>	Normal mode		900	1800	mA
		Low power mode		10		
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		2.35	4.7		μF

**LDO1 (600mA NMOS) (continued)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 4.7μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.2V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		30		μV <sub>RMS</sub>
		V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.0V		60		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60		
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA			70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.0V, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 4.7μF		±5		%
		C <sub>OUT</sub> = 10μF		±3		
Output Line Transient	Normal mode, V <sub>OUT</sub> = 1.0V, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs	V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V		5		mV
		V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V to 1.5V to 1.8V		5		
Output Startup Ramp Rate	10% to 90%			30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled.			5		μs
Output Overshoot during Startup Overshoot				50		mV
Output Active Discharge Resistance	(Note 10)			100		Ω
Thermal Shutdown	T <sub>J</sub> rising			165		°C
	T <sub>J</sub> falling			150		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches			87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches			5		%

**LDO2 (150mA NMOS)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 1.0μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub> must be lower than or equal to V <sub>SYS</sub>		V <sub>OUT</sub>		V <sub>SYS</sub>	V
	V <sub>SYS</sub>		2.6		5.5	
	(Note 7)		1.5			
Input Supply Current	Normal mode, no load			2		μA
	Low power mode, no load			2		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			25		μA
	Low power mode, no load			3		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.6		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			2.1875		
	Least significant step size			0.0125		
Output Voltage Accuracy	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		150			mA
	Low power mode		5			
Load Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V)	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	0.5			%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	0.5			
Line Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), I <sub>OUT</sub> = 0.1mA	Normal mode	0.05			%/ <i>V</i>
		Low power mode	0.05			
Dropout Voltage	Normal mode, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>	V <sub>SYS</sub> - V <sub>OUT</sub> = 2.5V	60	150		mV
		V <sub>SYS</sub> - V <sub>OUT</sub> = 1.5V	100			
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT</sub> (TARGET)	Normal mode	225	450		mA
		Low power mode	10			
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		0.5	1.0		μF

**LDO2 (150mA NMOS) (continued)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 1.0μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.2V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		30	μV <sub>RMS</sub>
		V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.0V		60	
		V <sub>SYS</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60	
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA		70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.0V, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 1.0μF		±5	%
		C <sub>OUT</sub> = 10μF		±3	
Output Line Transient	Normal mode, V <sub>OUT</sub> = 1.0V, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs	V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V		5	mV
		V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V to 1.5V to 1.8V		5	
Output Startup Ramp Rate	10% to 90%		30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled.		5		μs
Output Overshoot During Startup Overshoot			50		mV
Output Active Discharge Resistance	(Note 10)		100		Ω
Thermal Shutdown	T <sub>J</sub> rising		165		°C
	T <sub>J</sub> falling		150		
<b>POWER-OK COMPARATOR</b>					
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches		87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches		5		%

**LDO3 (450mA NMOS)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 4.7μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub> must be lower than or equal to V <sub>SYS</sub>		V <sub>OUT</sub>		V <sub>SYS</sub>	V
	V <sub>SYS</sub>		2.6		5.5	
	(Note 7)		1.5			
Input Supply Current	Normal mode, no load			2		μA
	Low power mode, no load			2		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			25		μA
	Low power mode, no load			3		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.6		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			2.1875		
	Least significant step size			0.0125		
Output Voltage Accuracy	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		450			mA
	Low power mode		5			
Load Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V)	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	0.5			%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	0.5			
Line Regulation	V <sub>SYS</sub> ≥ V <sub>OUT</sub> + 1.5V (V <sub>SYSTEMIN</sub> = 2.6V), I <sub>OUT</sub> = 0.1mA	Normal mode	0.05			%V
		Low power mode	0.05			
Dropout Voltage	Normal Mode, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>	V <sub>SYS</sub> - V <sub>OUT</sub> = 2.5V	60	150		mV
		V <sub>SYS</sub> - V <sub>OUT</sub> = 1.5V	100			
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT</sub> (TARGET)	Normal mode	675	1350		mA
		Low power mode	10			
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		2.35	4.7		μF

**LDO3 (450mA NMOS) (continued)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 1.0μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.2V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		30		μV <sub>RMS</sub>
		V <sub>SYS</sub> = 2.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.0V		60		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60		
Power-Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA			70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V, V <sub>OUT</sub> = 1.2V, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 4.7μF		±5		%
		C <sub>OUT</sub> = 10μF		±3		
Output Line Transient	Normal mode, V <sub>OUT</sub> = 1.2V, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs	V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V		5		mV
		V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 1.8V to 1.5V to 1.8V		5		
Output Startup Ramp Rate	10% to 90%			30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled			5		μs
Output Overshoot during Startup Overshoot				50		mV
Output Active Discharge Resistance	(Note 10)			100		Ω
Thermal Shutdown	T <sub>J</sub> rising			165		°C
	T <sub>J</sub> falling			150		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches			87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches			5		%

**LDO4, LDO5 and LDO7 (300mA PMOSLV)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 4.7μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub> must be lower than or equal to V <sub>SYS</sub>		1.7		V <sub>SYS</sub>	V
Input Supply Current	Normal mode, no load			15		μA
	Low power mode, no load			1.5		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			3		μA
	Low power mode, no load			0.3		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.8		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			3.975		
	Least significant step size			0.025		
Output Voltage Accuracy	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		300			mA
	Low power mode		5			
Load Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>		0.5		%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA		0.5		
Line Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub> , I <sub>OUT</sub> = 0.1mA	Normal mode		0.05		%V
		Low power mode		0.05		
Dropout Voltage	Normal mode, V <sub>SYS</sub> = 3.7V, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>	V <sub>INLx</sub> = 3.7V		60	150	mV
		V <sub>INLx</sub> = 1.7V		100		
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT(TARGET)</sub>	Normal mode		600	1120	mA
		Low power mode		40		
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		2.35	4.7		μF



**LDO4, LDO5 and LDO7 (300mA PMOSLV) (continued)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 4.7μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNIT
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		25		μV <sub>RMS</sub>
		V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 1.0V		30		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 2.0V		40		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = 3.0V		60		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60		
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA			70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 4.7μF		±5		%
		C <sub>OUT</sub> = 10μF		±3		
Output Line Transient	Normal mode, V <sub>OUT</sub> = 1.2V, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs	V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V		5		mV
		V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 2.0V to 1.7V to 2.0V		5		
Output Startup Ramp Rate	10% to 90%			30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled			5		μs
Output Over-shoot during Startup Over-shoot				50		mV
Output Active Discharge Resistance	(Note 10)			100		Ω
Thermal Shutdown	T <sub>J</sub> rising			+165		°C
	T <sub>J</sub> falling			+150		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches			87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches			3		%

**LDO6, LDO8, and LDO9 (150mA PMOSLV)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub> must be lower than or equal to V <sub>SYS</sub>		1.7		V <sub>SYS</sub>	V
Input Supply Current	Normal mode, no load			15		μA
	Low power mode, no load			1.5		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			3		μA
	Low power mode, no load			0.3		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.8		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			3.975		
	Least significant step size			0.025		
Output Voltage Accuracy	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA,	-5		+5	
Maximum Output Current (Note 8)	Normal mode		150			mA
	Low power mode		5			
Load Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	0.5			%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	0.5			
Line Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub> , I <sub>OUT</sub> = 0.1mA	Normal mode	0.05			%V
		Low power mode	0.05			
Dropout Voltage	Normal mode, V <sub>SYS</sub> = 3.7V, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>	V <sub>INLx</sub> = 3.7V	60	150		mV
		V <sub>INLx</sub> = 1.7V	100			
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT(TARGET)</sub>	Normal mode	300	560		mA
		Low power mode	40			
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		1.1	2.2		μF

**LDO6, LDO8, and LDO9 (150mA PMOSLV) (continued)**(V<sub>SYS</sub> = V<sub>INLx</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		25		μV <sub>RMS</sub>
		V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 1.0V		30		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 2.0V		40		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = 3.0V		60		
		V <sub>SYS</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60		
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA			70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 2.2μF		±5		%
		C <sub>OUT</sub> = 10μF		±3		
Output Line Transient	Normal mode, V <sub>OUT</sub> = 1.2V, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs	V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V		5		mV
		V <sub>SYS</sub> = 3.7V, V <sub>INLx</sub> = 2.0V to 1.7V to 2.0V		5		
Output Startup Ramp Rate	10% to 90%			30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled			5		μs
Output Overshoot During Startup Overshoot				50		mV
Output Active Discharge Resistance	(Note 10)			100		Ω
Thermal Shutdown	T <sub>J</sub> rising			+165		°C
	T <sub>J</sub> falling			+150		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches			87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches			3		%

**LDO11, LDO14 and LDO15 (150mA PMOSLS)**(V<sub>SYS</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub>		2.6		5.5	V
	V <sub>SYS</sub>		2.6		5.5	
Input Supply Current	Normal mode, no load		15			μA
	Low power mode, no load		4			
	Shutdown		< 0.1			
System Supply Current	Normal mode, no load		3.25			μA
	Low power mode, no load		0.85			
	Shutdown		< 0.1			
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00		0.8			V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F		3.975			
	Least significant step size		0.025			
Output Voltage Accuracy	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		150			mA
	Low power mode		5			
Load Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	0.5			%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	0.5			
Line Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub> , I <sub>OUT</sub> = 0.1mA	Normal mode	0.05			%/ <i>V</i>
		Low power mode	0.05			
Dropout Voltage	Normal mode, V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>		100	200		mV
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT(TARGET)</sub>	Normal mode	300	560		mA
		Low power mode	40			
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		0.6	2.2		μF

**LDO11, LDO14 and LDO15 (150mA PMOSLS) (continued)**(V<sub>sys</sub> = V<sub>INLx</sub> = +3.7V, C<sub>sys</sub> = 1.0μF, C<sub>out</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>sys</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		25		μV <sub>RMS</sub>
		V <sub>sys</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 1.0V		30		
		V <sub>sys</sub> = V <sub>INLx</sub> = 2.7V, V <sub>OUT</sub> = 2.0V		40		
		V <sub>sys</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = 3.0V		60		
		V <sub>sys</sub> = V <sub>INLx</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60		
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA			70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>sys</sub> = V <sub>INLx</sub> = 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 2.2μF		±5		%
		C <sub>OUT</sub> = 10μF		±3		
Output Line Transient	Normal mode, V <sub>INLx</sub> = 3.7V to 3.2V to 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs			5		mV
Output Startup Ramp Rate	10% to 90%			30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 to output rising, REFBYP enabled > 300μs prior to LDO being enabled			5		μs
Output Overshoot During Startup Overshoot				50		mV
Output Active Discharge Resistance	(Note 10)			100		Ω
Thermal Shutdown	T <sub>J</sub> rising			165		°C
	T <sub>J</sub> falling			150		
<b>POWER-OK COMPARATOR</b>						
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches			87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches			3		%

**LDO10, LDO12 and LDO13 (300mA PMOSLS)**(V<sub>SYS</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

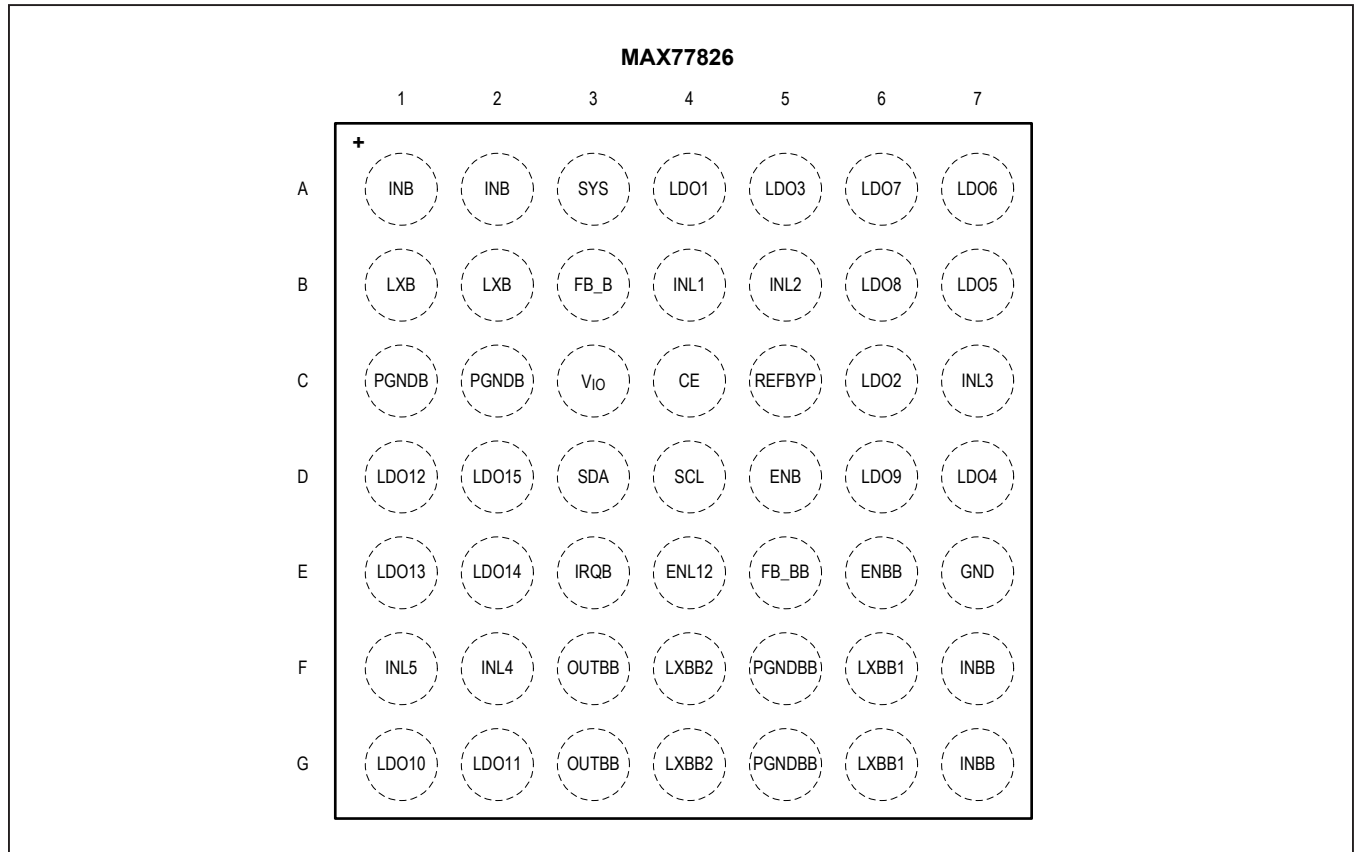
PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V <sub>INLx</sub>		2.6		5.5	V
	V <sub>SYS</sub>		2.6		5.5	
Input Supply Current	Normal mode, no load			15		μA
	Low power mode, no load			4		
	Shutdown			< 0.1		
System Supply Current	Normal mode, no load			3.25		μA
	Low power mode, no load			0.85		
	Shutdown			< 0.1		
Output Voltage Programming	Minimum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h00			0.8		V
	Maximum V <sub>OUT</sub> , Lx_VOUT[6:0] = 7'h7F			3.975		
	Least significant step size			0.025		
Output Voltage Accuracy	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub>	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	-2		+2	%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	-5		+5	
Maximum Output Current (Note 8)	Normal mode		300			mA
	Low power mode		5			
Load Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V	Normal mode I <sub>OUT</sub> = 0.1mA to I <sub>MAX</sub>	0.5			%
		Low power mode I <sub>OUT</sub> = 0.1mA to 5mA	0.5			
Line Regulation	V <sub>INLx</sub> = V <sub>OUT</sub> + 0.3V to V <sub>SYS</sub> , I <sub>OUT</sub> = 0.1mA	Normal mode	0.05			% / V
		Low power mode	0.05			
Dropout Voltage	Normal mode, V <sub>SYS</sub> = V <sub>INLx</sub> = 3.7V, I <sub>OUT</sub> = I <sub>MAX</sub> , V <sub>DO</sub> = V <sub>INLx</sub> - V <sub>OUT</sub>			100	200	mV
Output Current Limit	V <sub>OUT</sub> = 90% of V <sub>OUT(TARGET)</sub>	Normal mode		600	1120	mA
		Low power mode		40		
Output Capacitance for Stability	DCR < 200mΩ, ESL < 20nH (Note 9)		0.6	2.2		μF

**LDO10, LDO12 and LDO13 (300mA PMOSLS) (continued)**(V<sub>SYS</sub> = +3.7V, C<sub>SYS</sub> = 1.0μF, C<sub>OUT</sub> = 2.2μF, C<sub>REFBYP</sub> = 100nF, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 5)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output Noise	Normal mode, f = 10Hz to 100kHz, I <sub>OUT</sub> = 10% of I <sub>MAX</sub>	V <sub>SYS</sub> = V <sub>INLX</sub> = 2.7V, V <sub>OUT</sub> = V <sub>OUTMIN</sub>		25	μV <sub>RMS</sub>
		V <sub>SYS</sub> = V <sub>INLX</sub> = 2.7V, V <sub>OUT</sub> = 1.0V		30	
		V <sub>SYS</sub> = V <sub>INLX</sub> = 2.7V, V <sub>OUT</sub> = 2.0V		40	
		V <sub>SYS</sub> = V <sub>INLX</sub> = 3.7V, V <sub>OUT</sub> = 3.0V		60	
		V <sub>SYS</sub> = V <sub>INLX</sub> = 5.5V, V <sub>OUT</sub> = V <sub>OUTMAX</sub>		60	
Power Supply Rejection	Normal mode, f = 1kHz, I <sub>OUT</sub> = 30mA		70		dB
Output Load Transient (ΔV/V <sub>OUT</sub> )	Normal mode, V <sub>SYS</sub> = V <sub>INLX</sub> = 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA to ½ x I <sub>MAX</sub> to 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 1μs	C <sub>OUT</sub> = 2.2μF		±5	%
		C <sub>OUT</sub> = 10μF		±3	
Output Line Transient	Normal mode, V <sub>INLX</sub> = 3.7V to 3.2V to 3.7V, V <sub>OUT</sub> = default, I <sub>OUT</sub> = 1mA, t <sub>RISE</sub> = t <sub>FALL</sub> = 5μs		5		mV
Output Startup Ramp Rate	10% to 90%		30		mV/μs
Turn-On Delay Time	From Lx_EN = 1 (or ENL12 = high) to output rising, REFBYP enabled > 300μs prior to LDO being enabled		5		μs
Output Overshoot During Startup Overshoot			50		mV
Output Active Discharge Resistance	(Note 10)		100		Ω
Thermal Shutdown	T <sub>J</sub> rising		+165		°C
	T <sub>J</sub> falling		+150		
<b>POWER-OK COMPARATOR</b>					
Output POK Trip Level	Rising edge, V <sub>OUT</sub> when V <sub>POK</sub> switches		87.5		%
Output POK Hysteresis	V <sub>OUT</sub> when V <sub>POK</sub> switches		3		%

**Note 3:** Guaranteed by design. Not production tested.**Note 4:** 100% production tested at T<sub>A</sub> = +25°C, limits over the operating range are guaranteed by design.**Note 5:** Limits are 100% production tested at T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed through correlation using statistical quality control methods.**Note 6:** The maximum output current spec is not directly tested. Instead, it is guaranteed by LX NMOS current limit test.**Note 7:** For NMOS LDOs, V<sub>SYS</sub> must be at least 1.5V above V<sub>OUT</sub> (V<sub>SYS</sub> ≥ V<sub>OUT</sub> + 1.5V).**Note 8:** The maximum output current is guaranteed by the output voltage accuracy tests.**Note 9:** For stability, guaranteed by design and not production tested.**Note 10:** There is an n-channel MOSFET in series with the output active discharge resistance. This NMOS requires V<sub>SYS</sub> > 1.2V to be enhanced.

### Pin Configurations



### Pin Description

PIN	NAME	FUNCTION
C4	CE	Active-High Chip Enable Input. When CE = high (standby), the I <sup>2</sup> C interface is enabled and regulators are ready to be turned on. When CE = low (shutdown), all regulators are turned off and all Type-O registers are reset to their POR default values.
D5	ENB	Active-High BUCK External Enable Input. An 800kΩ internal pull-down resistance to the GND. If this pin is not used, leave it floating.
E6	ENBB	Active-High BUCK BOOST External Enable Input. An 800kΩ internal pulldown resistance to the GND. If this pin is not used, leave it unconnected.
E4	ENL12	Active-High LDO12 External Enable Input. An 800kΩ internal pulldown resistance to the GND. If this pin is not used, leave it unconnected.
B3	FB_B	BUCK Output Voltage Feedback
E5	FB_BB	BUCK BOOST Output Voltage Feedback
E7	GND	Ground
A1, A2	INB	BUCK Input. Bypass to PGNDB with a 10μF capacitor.
F7, G7	INBB	BUCK BOOST Input



## Pin Description (continued)

PIN	NAME	FUNCTION
B4	INL1	Input for LDO1 and 2. Bypass to GND with a 4.7 $\mu$ F capacitor.
B5	INL2	Input for LDO3. Bypass to GND with a 1 $\mu$ F capacitor.
C7	INL3	Input for LDO4, 5, 6, 7, 8, and 9. Bypass to GND with a 4.7 $\mu$ F capacitor.
F2	INL4	Input for LDO10 and 11. Bypass to GND with a 4.7 $\mu$ F capacitor.
F1	INL5	Input for LDO12, 13, 14, and 15. Bypass to GND with a 4.7 $\mu$ F capacitor.
E3	IRQB	Interrupt Output. A 100k $\Omega$ external pullup resistor to V <sub>IO</sub> is required.
B1, B2	LXB	BUCK Switching Node
F6, G6	LXBB1	BUCK BOOST Switching Node 1
F4, G4	LXBB2	BUCK BOOST Switching Node 2
A4	LDO1	LDO1 (600mA NMOS) Output. Bypass to GND with a 4.7 $\mu$ F capacitor.
C6	LDO2	LDO2 (150mA NMOS) Output. Bypass to GND with a 1 $\mu$ F capacitor.
A5	LDO3	LDO3 (450mA NMOS) Output. Bypass to GND with a 4.7 $\mu$ F capacitor.
D7	LDO4	LDO4 (300mA PMOSLV) Output. Bypass to GND with a 4.7 $\mu$ F capacitor.
B7	LDO5	LDO5 (300mA PMOSLV) Output. Bypass to GND with a 4.7 $\mu$ F capacitor.
A7	LDO6	LDO6 (150mA PMOSLV) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
A6	LDO7	LDO7 (300mA PMOSLV) Output. Bypass to GND with a 4.7 $\mu$ F capacitor.
B6	LDO8	LDO8 (150mA PMOSLV) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
D6	LDO9	LDO9 (150mA PMOSLV) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
G1	LDO10	LDO10 (300mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
G2	LDO11	LDO11 (150mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
D1	LDO12	LDO12 (300mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
E1	LDO13	LDO13 (300mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
E2	LDO14	LDO14 (150mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
D2	LDO15	LDO15 (150mA PMOSLS) Output. Bypass to GND with a 2.2 $\mu$ F capacitor.
F3, G3	OUTBB	BUCK BOOST Output
C1, C2	PGNDB	BUCK Power GND
F5, G5	PGNDBB	BUCK BOOST Power GND
C5	REFBYP	LDO Reference Bypass Node. Connect a 0.1 $\mu$ F Cap to GND.
D4	SCL	I <sup>2</sup> C Clock Input. High Impedance in Off State. A 1.5k $\Omega$ –2.2k $\Omega$ of pullup resistor to V <sub>IO</sub> is required.
D3	SDA	I <sup>2</sup> C Data I/O. High Impedance in Off State. A 1.5k $\Omega$ –2.2k $\Omega$ of pullup resistor to V <sub>IO</sub> is required.
A3	SYS	System (Battery) Voltage Input. Bypass to GND with a 1 $\mu$ F capacitor.
C3	V <sub>IO</sub>	IO Supply Voltage Input. Bypass to GND with a 0.1 $\mu$ F capacitor.

Block Diagram

